

L Number	Hits	Search Text	DB	Time stamp
1	13348	cmp	USPAT; US-PGPUB	2002/05/07 15:04
2	65447	substrate adj2 surface	USPAT; US-PGPUB	2002/05/07 15:05
3	458	cmp with (substrate adj2 surface)	USPAT; US-PGPUB	2002/05/07 15:05
4	6378	sti or "trench isolation"	USPAT; US-PGPUB	2002/05/07 15:05
5	120	(cmp with (substrate adj2 surface)) and (sti or "trench isolation")	USPAT; US-PGPUB	2002/05/07 15:51
6	391	(438/435,437).CCLS.	USPAT; US-PGPUB	2002/05/07 15:52
7	13	(cmp with (substrate adj2 surface)) and ((438/435,437).CCLS.)	USPAT; US-PGPUB	2002/05/07 17:27
8	544	polyimide with thermoset	USPAT; US-PGPUB	2002/05/07 17:39
9	70002	encapsulation or encapsulated	USPAT; US-PGPUB	2002/05/07 17:39
10	109811	voids or bubbles	USPAT; US-PGPUB	2002/05/07 17:39
11	395724	vacuum	USPAT; US-PGPUB	2002/05/07 17:40
12	2604	(encapsulation or encapsulated) and (voids or bubbles) and vacuum	USPAT; US-PGPUB	2002/05/07 17:40
13	3519.6	resin	USPAT; US-PGPUB	2002/05/07 17:40
14	501.9	(voids or bubbles) with resin	USPAT; US-PGPUB	2002/05/07 17:40
15	506	(438/127).CCLS.	USPAT; US-PGPUB	2002/05/07 17:40
16	32	((voids or bubbles) with resin) and ((438/127).CCLS.)	USPAT; US-PGPUB	2002/05/07 17:41

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5	120	(cmp with (substrate adj2 surface)) and (sti or "trench isolation")	USPAT; US-PGPUB	2002/05/07 15:51
6	391	((438/435,437).CCLS.	USPAT; US-PGPUB	2002/05/07 15:52
7	13	(cmp with (substrate adj2 surface)) and ((438/435,437).CCLS.)	USPAT; US-PGPUB	2002/05/07 17:27
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10	109811	voids or bubbles	USPAT; US-PGPUB	2002/05/07 17:39
11	395724	vacuum	USPAT; US-PGPUB	2002/05/07 17:40
12	2604	(encapsulation or encapsulated) and (voids or bubbles) and vacuum	USPAT; US-PGPUB	2002/05/07 19:25
13	351986	resin	USPAT; US-PGPUB	2002/05/07 17:40
14	5059	(voids or bubbles) with resin	USPAT; US-PGPUB	2002/05/07 17:40
15	566	((438/127).CCLS.	USPAT; US-PGPUB	2002/05/07 17:40
16	3	(voids or bubbles) with resin) and ((438/127).CCLS.)	USPAT; US-PGPUB	2002/05/07 19:22
18	3279	"integrated circuit" or semiconductor	USPAT; US-PGPUB	2002/05/07 19:24
17	2	bumps with resin with (heating or heated or heat) with (void or cavity)	USPAT; US-PGPUB	2002/05/07 19:24
19	6	bumps with resin with (heating or heated or heat) with voids	USPAT; US-PGPUB	2002/05/07 19:24
0	669	(encapsulation or encapsulated) and (voids or bubbles) and vacuum) and ("integrated circuit" or semiconductor)	USPAT; US-PGPUB	2002/05/07 19:25
1	11905	packaging	USPAT; US-PGPUB	2002/05/07 19:26
2	21	((encapsulation or encapsulated) and (voids or bubbles) and vacuum) and ("integrated circuit" or semiconductor)) and packaging	USPAT; US-PGPUB	2002/05/07 19:32
3	199	bumps	USPAT; US-PGPUB	2002/05/07 19:32
4	7	((encapsulation or encapsulated) and (voids or bubbles) and vacuum) and ("integrated circuit" or semiconductor)) and packaging) and bumps	USPAT; US-PGPUB	2002/05/07 19:34
5	1	voids or bubbles) with bumps	USPAT; US-PGPUB	2002/05/07 19:34
6		((encapsulation or encapsulated) and (voids or bubbles) and vacuum) and ("integrated circuit" or semiconductor)) and packaging) and bumps) and ((voids or bubbles) with bumps)	USPAT; US-PGPUB	2002/05/07 19:34